

# 110169 - 00

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# **Product Change Notification**

Change Notification #:	110169 - 00
Change Title:	Intel® Tray Packed Products, PCN
	110169-00, Transport Media, Converting
	to a Universal Plastic Shim
Date of Publication:	April 06, 2012

#### Key Characteristics of the Change:

Transport Media

#### **Forecasted Key Milestones:**

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Date of First Availability of Post-Conversion Material:	May 07, 2012

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

#### **Description of Change to the Customer:**

Intel is converting from a corrugated cardboard shim to a plastic shim with one thickness (eliminating "thick" and "thin" shims). The shim is black in color and meets JEDEC standard ESD criteria. The JEDEC dimensions will change as follows:

	Length (mm)	Width (mm)
Current:	327	140
New:	328	140

Thick	iness (mr	n)		
6.2	(thick)	/	1.7	(thin)
4.0				



One shim is placed on top of the tray stack and a second shim is placed on the bottom of the tray stack when packaged for shipping.



# **Customer Impact of Change and Recommended Action:**

Intel anticipates no impact to customers. Customers will continue to see thick and thin corrugated cardboard shims until the current inventory is depleted. The new plastic shims are environmentally compliant and can be recycled.

### **Products Affected / Intel Ordering Codes:**

All Intel® tray packed component products are affected.

## **PCN Revision History:**

Date of Revision:	<b>Revision Number:</b>	Reason:
April 6, 2012	00	Originally Published PCN